

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF:

APPLICATION NO.:

STEPHEN MOXHAM AND

WILLIAM STEPHENSON

10/034,924

FILED:

FOR:

DECEMBER 26, 2001

DECEMBER 20, 200

METHOD AND APPARATUS FOR SUPPORTING MICROELECTRONIC

SUBSTRATES

EXAMINER: ALEXANDER O.

WILLIAMS

ART UNIT: 2826

CONF. NO: 1417

Supplemental Information Disclosure Statement
As Submission Under 37 C.F.R. § 1.114

Mail Stop RCE Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

1. <u>Timing of Submission</u>

This information disclosure is being filed with a Request for Continued Examination under 37 C.F.R. § 1.114. The references listed on the enclosed Form PTO-1449 (modified) may be material to the examination of this application; the Examiner is requested to make them of record in the application.

Copies of the following references are enclosed:

2. Cited Information

Ľ.	Copies	of the following references are enclosed.
		All cited references References marked by an asterisk (*)
<u>.</u>	unders commo citing t langua prepar English repres	ollowing references are not in English. For each such reference, the signed has enclosed (i) a translation of the reference; (ii) a copy of a unication from a foreign patent office or International Searching Authority he reference, (iii) a copy of a reference which appears to be an Englishinge counterpart, or (iv) an English-language abstract for the reference ed by a third party. Applicant has not verified that the translation, in-language counterpart or third-party abstract is an accurate entation of the teachings of the non-English reference, though, and less the right to demonstrate otherwise.
		All cited references References marked by a pound sign (#)

3. Effect of Information Disclosure Statement (37 CFR 1.97(h))

This Information Disclosure Statement is not to be construed as a representation that: (i) a search has been made; (ii) additional information material to the examination of this application does not exist; (iii) the information, protocols, results and the like reported by third parties are accurate or enabling; or (iv) the cited information is, or is considered to be, material to patentability. In addition, applicant does not admit that any enclosed item of information constitutes prior art to the subject invention and specifically reserves the right to demonstrate that any such reference is not prior art.

4. Fee Payment

No fees are believed due. However, should the Commissioner determine that fees are due in order for this Information Disclosure Statement to be considered, the Commissioner is hereby authorized to charge such fees to Deposit Account No. 50-0665.

5. Patent Term Adjustment (37 CFR 1.704(d))

The undersigned states that each item of information submitted herewith was
cited in a communication from a foreign patent office in a counterpart
application and that this communication was not received by any individual
designated in 37 C.F.R. § 1.56(c) more than thirty days prior to the filing of this
statement. 37 C.F.R. § 1.704(d).

Respectfully submitted,

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Attorney Docket No. 108298633US Disclosure No. 01-0389

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Ì			Application Number	10/034,924	
4	DISCLOSURE		Confirmation Number	1417	
STATEMENT E	BY APPLICANT		Filing Date	December 26, 2001	
	149 (Modified)		First Named Inventor	Stephen Moxham	
Use several sheets if necessary)			Group Art Unit	2826	
			Examiner Name	Alexander O. Williams	
1	of	2	Attorney Docket No.	108298633US	

				U	.S. PATENT DOCUMENTS			
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*EXAMINER:	Initial if reference considered, whether or not criteria is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to application(s).			

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INFORMATION DISCLOSURE STATEMENT BY APP'LICANT

Form PTO-1449 (Modified) (Use several sheets if necessary)

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	COMPLETE IF KNOWN		
Application Number	10/034,924		
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